

MATERIAL:

1. Base Housing : Thermoplastic, Flammability UL 94V-0.
2. Cover : Thermoplastic, Flammability UL 94V-0.
3. Contact : Copper Alloy
Finish: Gold Plating over 50u"min Ni under plating on contact area.
4. Solder ball: LF Solder ball
5. Handle:steel
6. Stiffener:steel
7. Load plate:steel

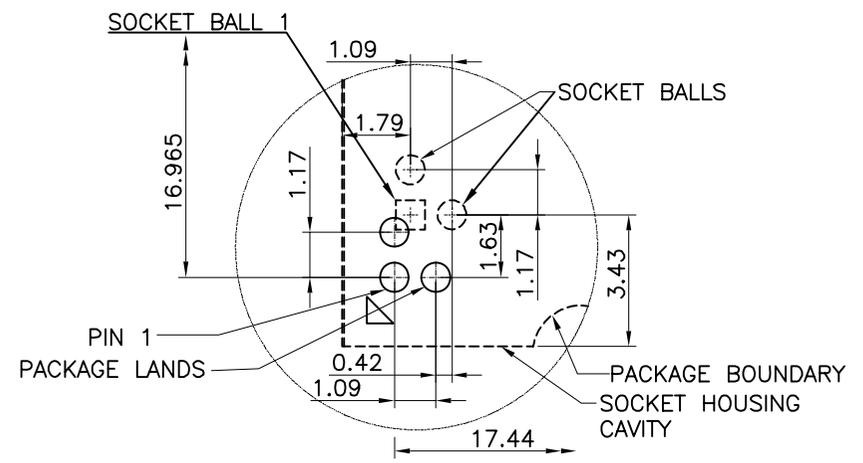
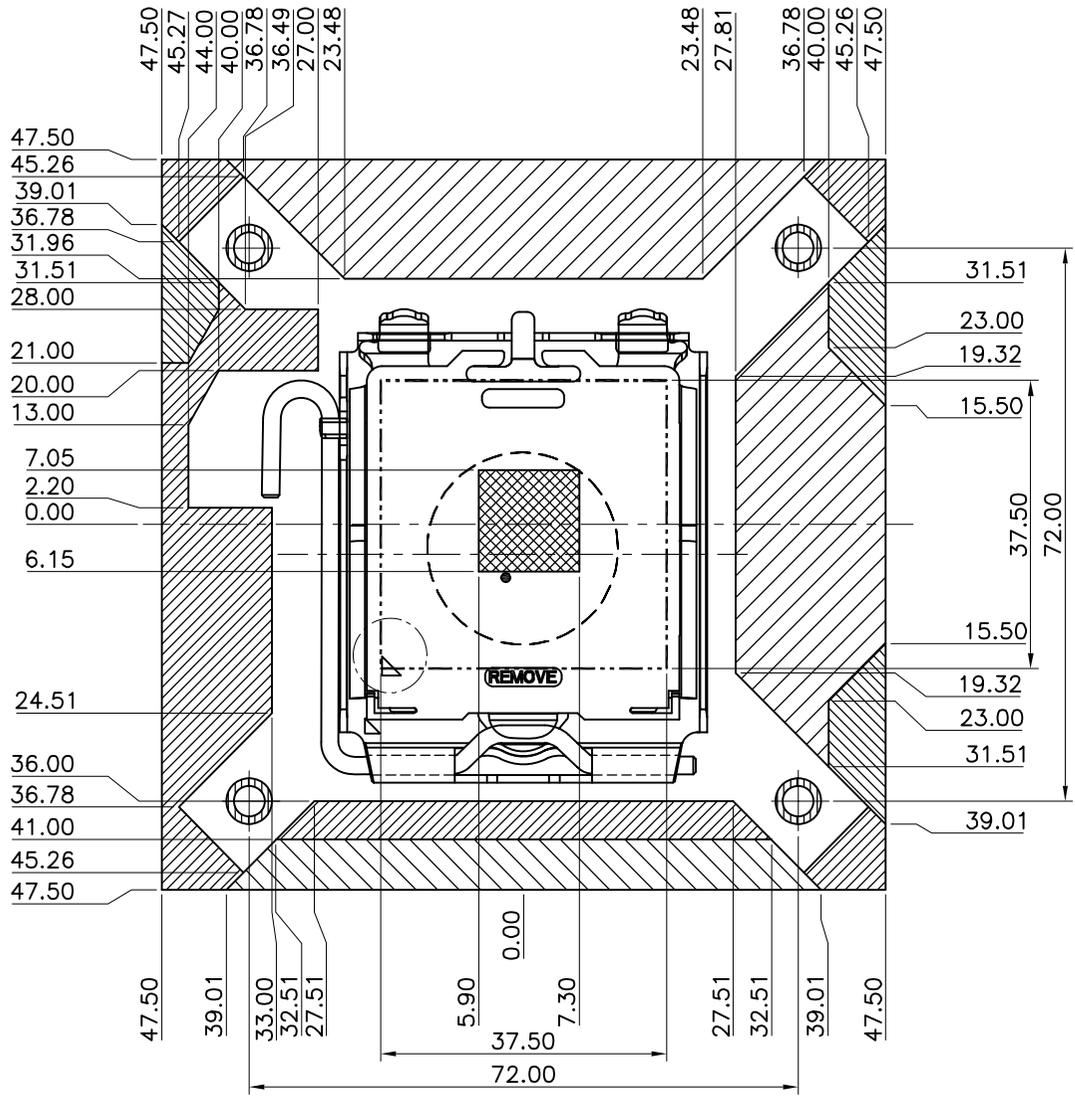
MPGA-VL-755-LF
LEADFREE

RoHS Compliant



煜倫股份有限公司

PART NO. MPGA-VL-755		CHECKED BY CY	TOLERANCES ARE .X ± 0.2 .XX ± .XXX ± AWG	DESCRIP TION: Land Grid Array(LGA)775 Position socket	AREA	REVISIONS	HK	DATE
DWG NO. MPGA-VL-755								
FILE NO.		UNIT / mm	SCALE 1:1	PROJECTION				



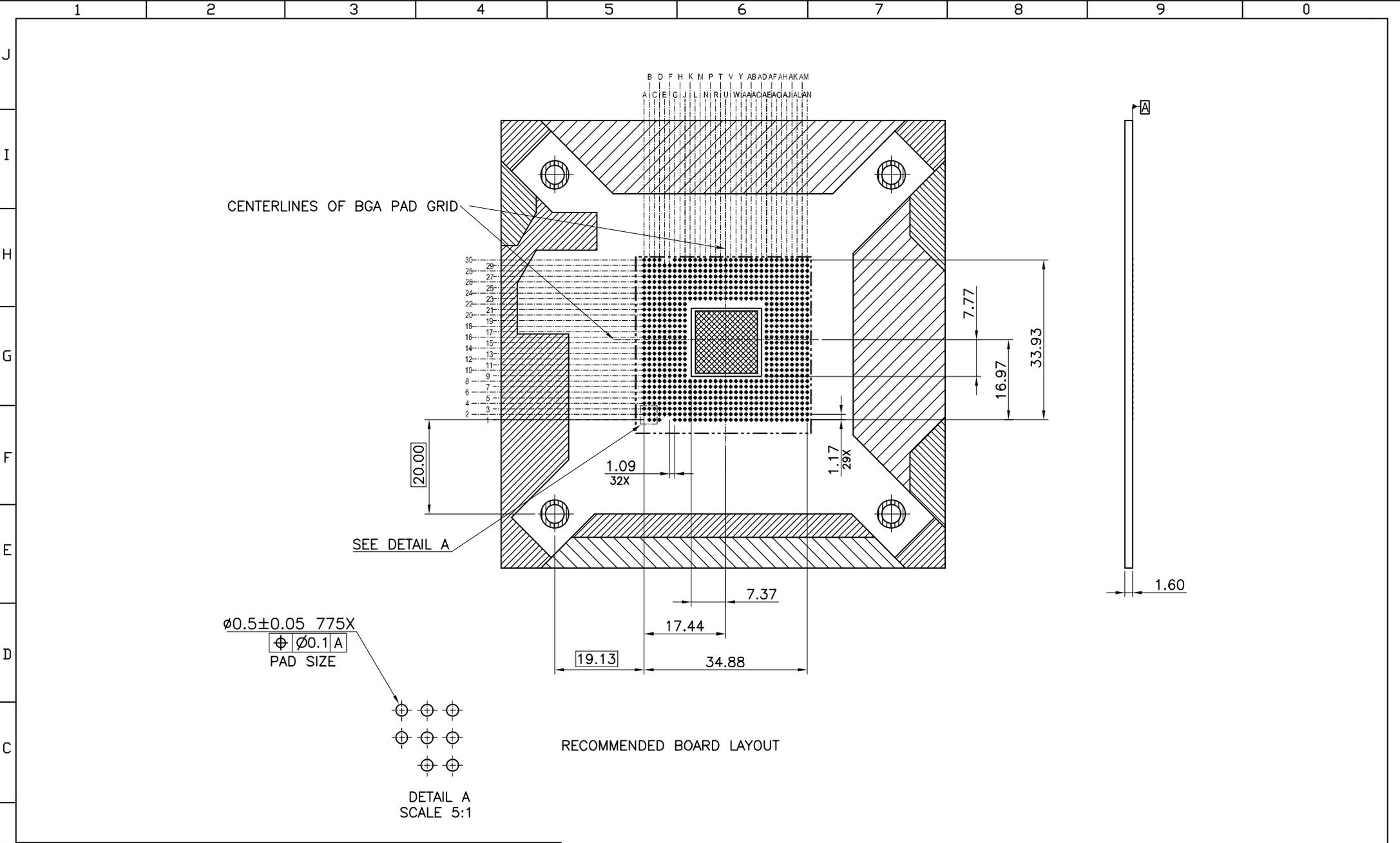
LEGEND	
	SOCKET/THERMO/MECHANICAL COMPONENT KEEP-INS
	10.0mm MAX. COMPONENT HEIGHT
	2.5mm MAX. COMPONENT HEIGHT
	6.0mm MAX. COMPONENT HEIGHT
	25.0mm MAX. COMPONENT HEIGHT
	1.8mm MAX. COMPONENT HEIGHT
	BOARD ROUTING KEEP-OUT

RECOMMENDED PCB KEEPOUT

MORETHANALL
CONNECTORS
ASSEMBLIES

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MORETHANALL
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PART NO. MPGA-VL-755

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TOLERANCES ARE
.X ± 0.2
.XX ±
.XXX ±
AWG

DESCRIPTION: Land Grid Array(LGA)775
Position socket

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UNIT / mm

SCALE 1:1

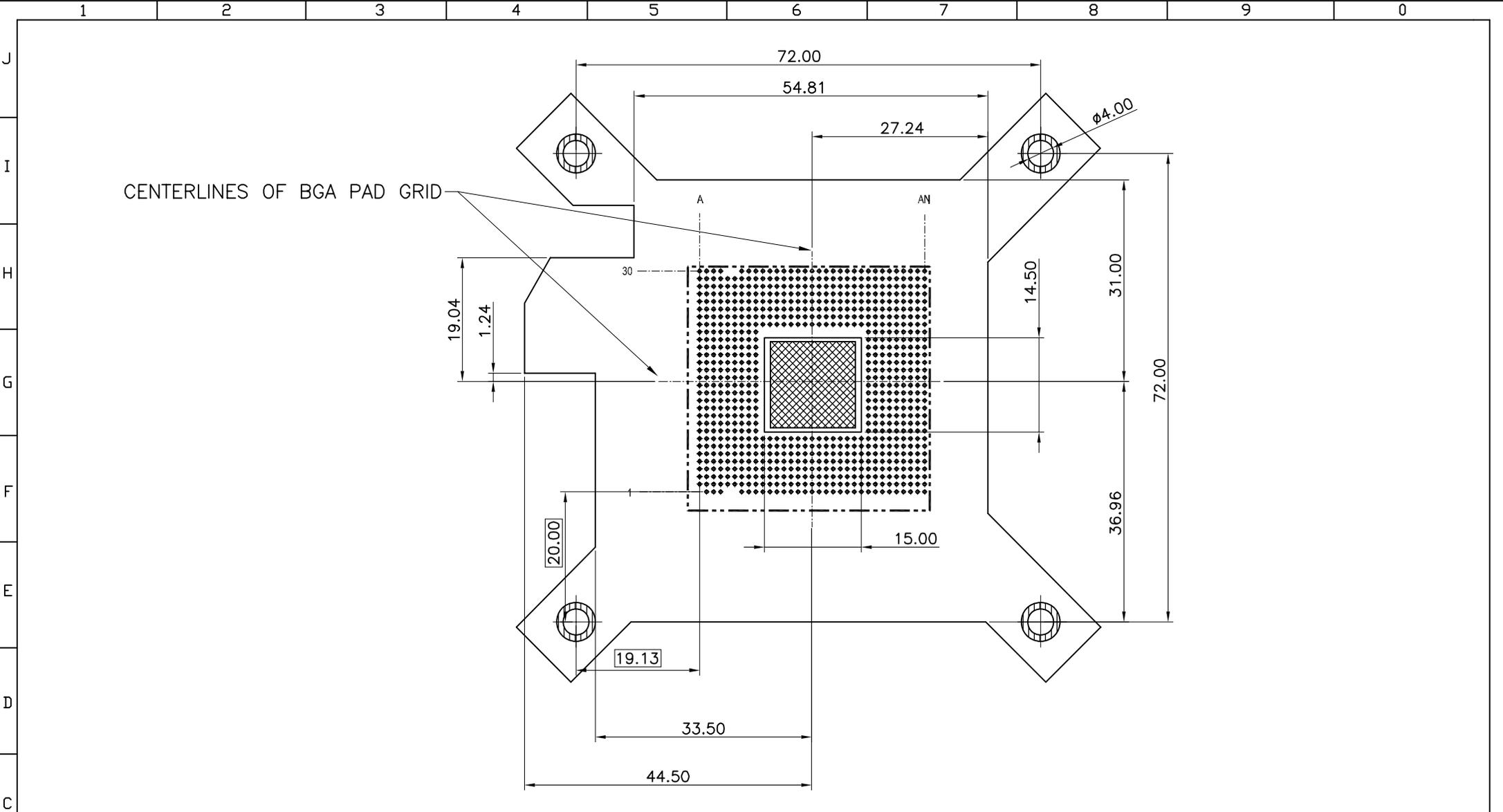
PROJECTION

AREA

REVISIONS

HK

DATE



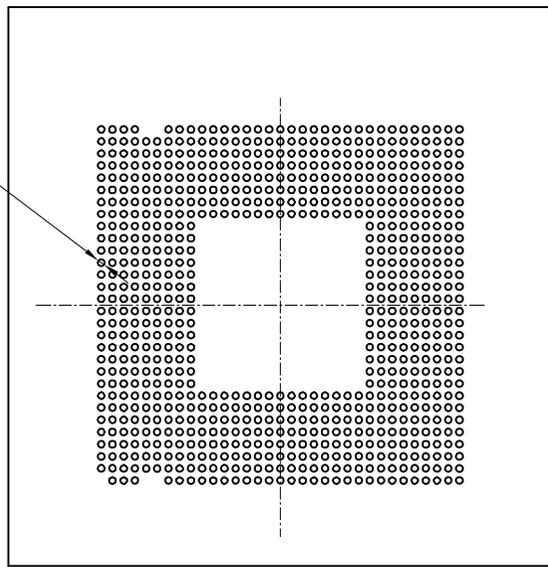
RECOMMENDED BOARD LAYOUT

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STENCIL THICK
0.15

STENCIL DIAMETER
ø0.65±0.05



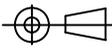
RECOMMENDED STENCIL

SOLDER TEMPERATURE REQUEST

- 1.Time: <100sec between 150~200degree
- 2.Time: 40~90sec above 220 degree
- 3.Peak temperature:
With Nitrogen:228-240 degree
Without Nitrogen:235-245 degree
- 4.Temperature slope:
A.Ave ramp-up rate 3 degree/sec max
B.Ramp down rate 3 degree/sec max
- 5.Concentration of Oxygen: 1000ppm max (In Nitrogen environment)



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